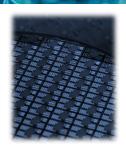
PDF SOLUTIONS

Exensio™ Defect Management







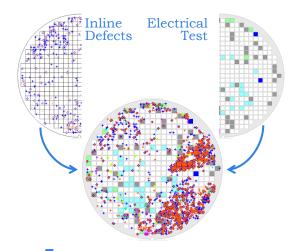
WAFER SORT



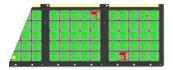
ASSEMBLY

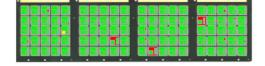


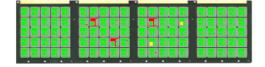
TEST



Strip Maps Tray Maps Panel Maps







End-to-End Defect and Yield Data



- Semiconductor-specific visualizations
- Many ready-to-go preconfigured templates
- Full end-to-end traceability of defect, wafer sort, assembly and final test with E142 compliance
 - Full support for Python, R, TERR, Matlab, C
 - 200+ data formats supported

Analytics and Root-Cause-Analysis Tools

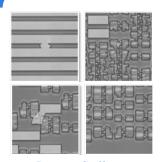
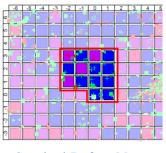
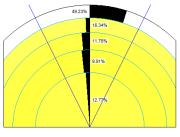


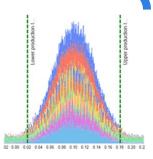
Image Gallery



Stacked Defect Maps



Zonal Maps



Charts and Plots

PDF SOLUTIONS

Exensio™ Defect Management

2858 De La Cruz Blvd, Santa Clara, CA 95050 USA

+1-408-280-7900

https://www.pdf.com

info@pdf.com

Managing defects found on wafers, reticles and substrates

Gain Visibility into yield-limiting factors, time trends and product quality

Focus on What Matters using correlation between inline defects, metrology and electrical wafer tests

Take Timely Action with powerful big-data analytics and visualizations

Streamline Processes with workflows and automation across your organization. Bring multiple factories and functions together to facilitate faster and more efficient decision making

Expedite Yield Ramp with insights into systematic versus random defects at the die-, reticle- and wafer-level

Improve IT Efficiency by managing end-to-end data from fab, mask shop, assembly line, test and EMS using our industry-proven and time-tested 100+ data loaders to handle all standard data types throughout the semiconductor supply chain

Increase Profitability by automated monitoring of defect and yield data by factory, equipment, product, operator and material

Exensio visualizations Powered by TIBCO®

services go to www.pdf.com

Also check out



Exensio DMS can be configured to connect to our industry-leading solutions on the <a href="Exensio" Platform: AIM", CV", Cimetrix", Sapience. Our Design-for-Inspection solutions DFI have been used by customers in over 120 tape outs to date. 100 million DUTs per hour can be tested for OPEN/SHORT — fast enough for inline inspection.

For more information on this or any PDF products or

Applications

- End-to-End Yield and Defect Management
- Process & Equipment Qualification and Monitoring
- Troubleshooting of low yields
- Defect binning and classification automation

Value

- Improve Product Quality
- Increase Fab Efficiency
- Avoid Fab Line-Down

